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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

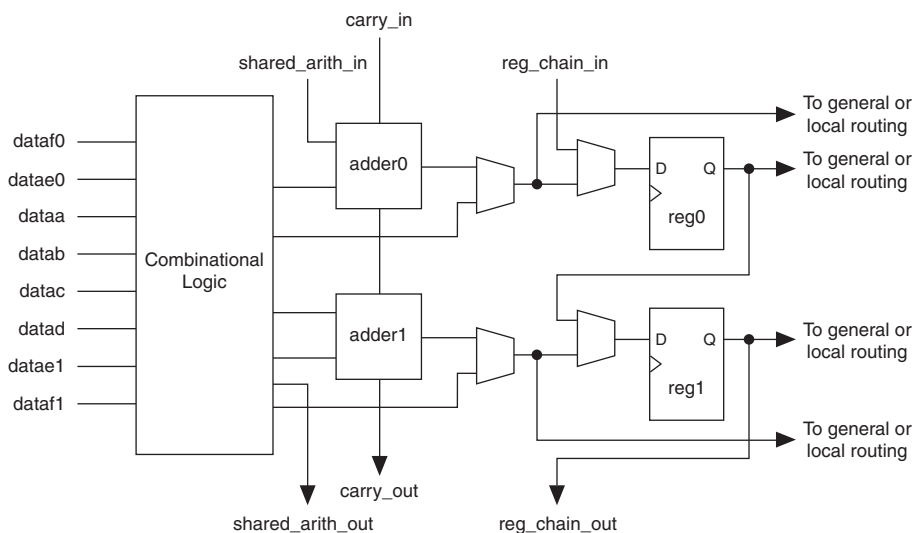
#### Details

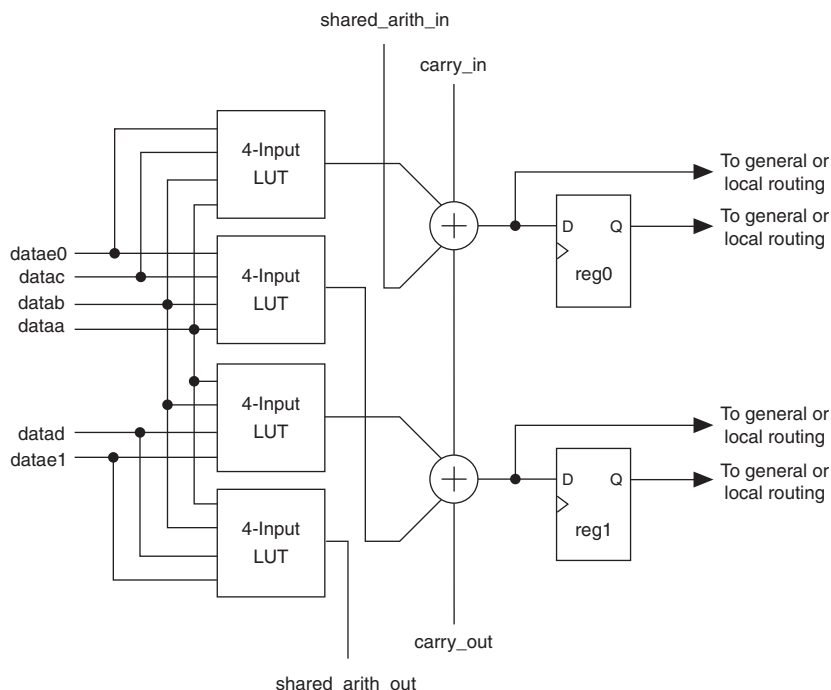
Product Status	Obsolete
Number of LABs/CLBs	8970
Number of Logic Elements/Cells	179400
Total RAM Bits	9383040
Number of I/O	742
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1020-BBGA
Supplier Device Package	1020-FBGA (33x33)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep2s180f1020i4n">https://www.e-xfl.com/product-detail/intel/ep2s180f1020i4n</a>

completely backward-compatible with four-input LUT architectures. One ALM can also implement any function of up to six inputs and certain seven-input functions.

In addition to the adaptive LUT-based resources, each ALM contains two programmable registers, two dedicated full adders, a carry chain, a shared arithmetic chain, and a register chain. Through these dedicated resources, the ALM can efficiently implement various arithmetic functions and shift registers. Each ALM drives all types of interconnects: local, row, column, carry chain, shared arithmetic chain, register chain, and direct link interconnects. [Figure 2-5](#) shows a high-level block diagram of the Stratix II ALM while [Figure 2-6](#) shows a detailed view of all the connections in the ALM.

**Figure 2-5. High-Level Block Diagram of the Stratix II ALM**

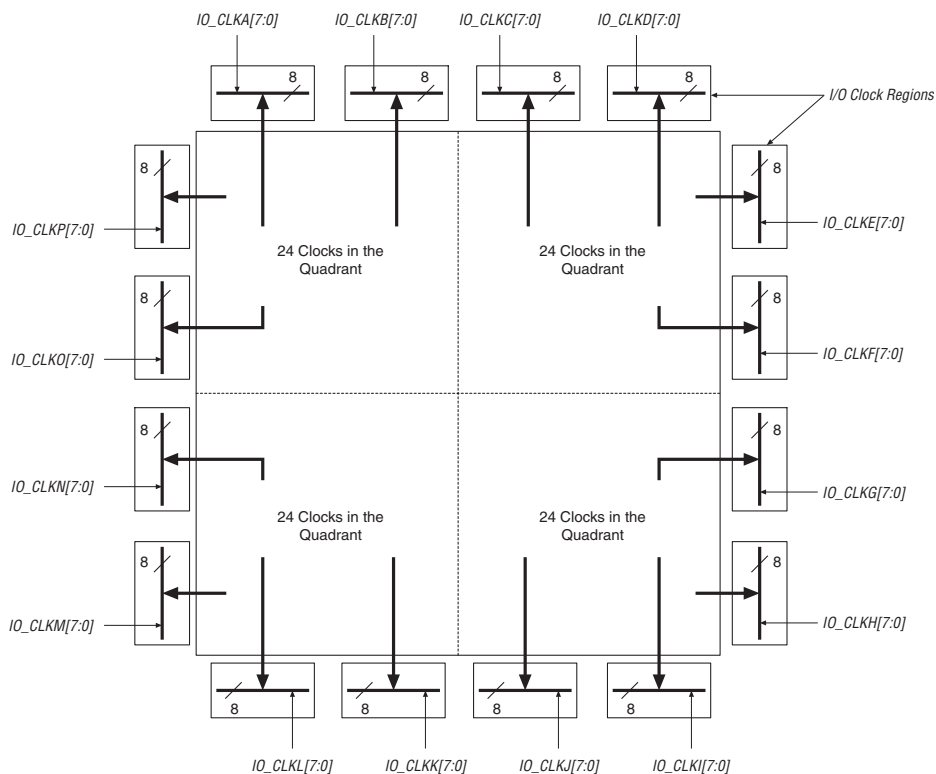


**Figure 2–13. ALM in Shared Arithmetic Mode****Note to Figure 2–13:**

- (1) Inputs dataae0 and dataae1 are available for register packing in shared arithmetic mode.

Adder trees can be found in many different applications. For example, the summation of the partial products in a logic-based multiplier can be implemented in a tree structure. Another example is a correlator function that can use a large adder tree to sum filtered data samples in a given time frame to recover or to de-spread data which was transmitted utilizing spread spectrum technology.

An example of a three-bit add operation utilizing the shared arithmetic mode is shown in Figure 2–14. The partial sum ( $S[2..0]$ ) and the partial carry ( $C[2..0]$ ) is obtained using the LUTs, while the result ( $R[2..0]$ ) is computed using the dedicated adders.

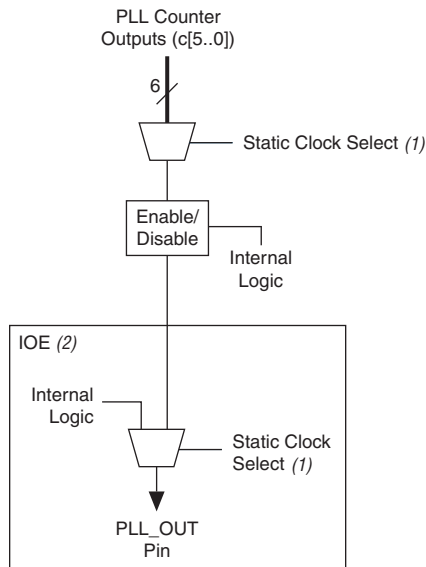
**Figure 2–36. EP2S60, EP2S90, EP2S130 & EP2S180 Device I/O Clock Groups**

You can use the Quartus II software to control whether a clock input pin drives either a global, regional, or dual-regional clock network. The Quartus II software automatically selects the clocking resources if not specified.

### *Clock Control Block*

Each global clock, regional clock, and PLL external clock output has its own clock control block. The control block has two functions:

- Clock source selection (dynamic selection for global clocks)
- Clock power-down (dynamic clock enable/disable)

**Figure 2–39. External PLL Output Clock Control Blocks****Notes to Figure 2–39:**

- (1) These clock select signals can only be set through a configuration file (.sof or .pof) and cannot be dynamically controlled during user mode operation.
- (2) The clock control block feeds to a multiplexer within the PLL\_OUT pin's IOE. The PLL\_OUT pin is a dual-purpose pin. Therefore, this multiplexer selects either an internal signal or the output of the clock control block.

For the global clock control block, the clock source selection can be controlled either statically or dynamically. The user has the option of statically selecting the clock source by using the Quartus II software to set specific configuration bits in the configuration file (.sof or .pof) or the user can control the selection dynamically by using internal logic to drive the multiplexor select inputs. When selecting statically, the clock source can be set to any of the inputs to the select multiplexor. When selecting the clock source dynamically, you can either select between two PLL outputs (such as the C0 or C1 outputs from one PLL), between two PLLs (such as the C0/C1 clock output of one PLL or the C0/C1 clock output of the other PLL), between two clock pins (such as CLK0 or CLK1), or between a combination of clock pins or PLL outputs. The clock outputs from corner PLLs cannot be dynamically selected through the global control block.

For the regional and PLL\_OUT clock control block, the clock source selection can only be controlled statically using configuration bits. Any of the inputs to the clock select multiplexor can be set as the clock source.

The Stratix II clock networks can be disabled (powered down) by both static and dynamic approaches. When a clock net is powered down, all the logic fed by the clock net is in an off-state thereby reducing the overall power consumption of the device.

The global and regional clock networks can be powered down statically through a setting in the configuration (**.sof** or **.pof**) file. Clock networks that are not used are automatically powered down through configuration bit settings in the configuration file generated by the Quartus II software.

The dynamic clock enable/disable feature allows the internal logic to control power up/down synchronously on GCLK and RCLK nets and PLL\_OUT pins. This function is independent of the PLL and is applied directly on the clock network or PLL\_OUT pin, as shown in [Figures 2-37 through 2-39](#).



The following restrictions for the input clock pins apply:

- CLK0 pin -> inclk[0] of CLKCTRL
- CLK1 pin -> inclk[1] of CLKCTRL
- CLK2 pin -> inclk[0] of CLKCTRL
- CLK3 pin -> inclk[1] of CLKCTRL

In general, even CLK numbers connect to the inclk[0] port of CLKCTRL, and odd CLK numbers connect to the inclk[1] port of CLKCTRL.

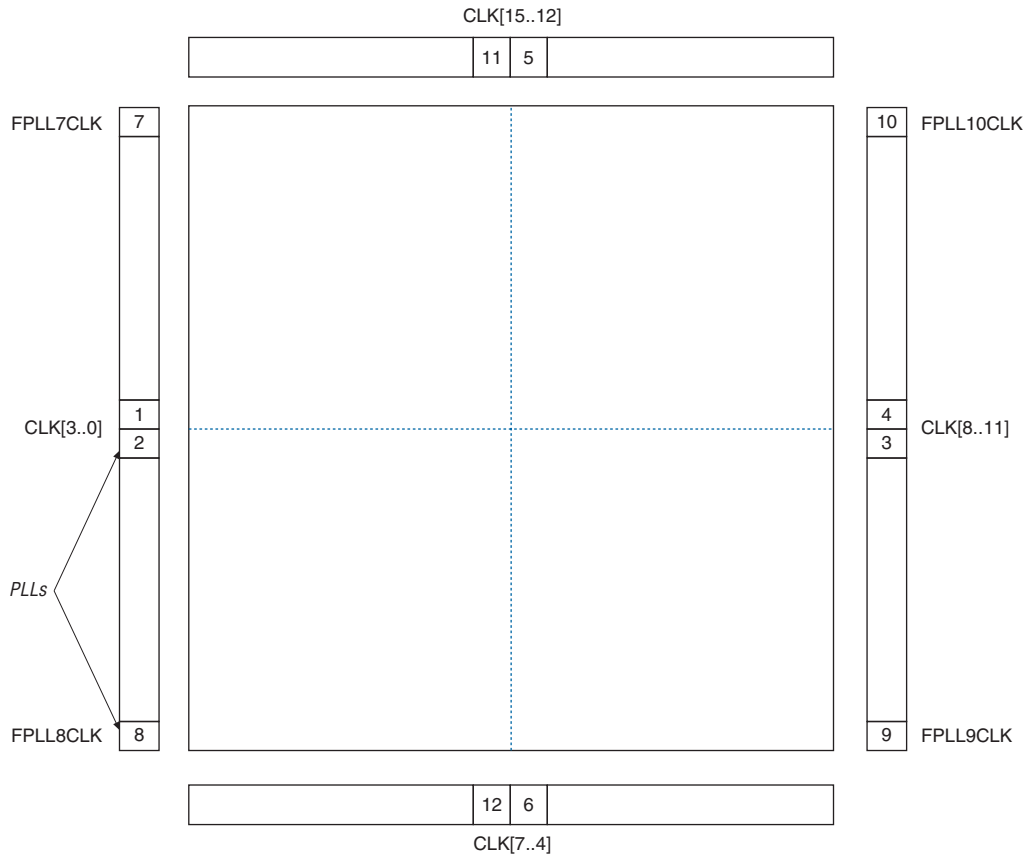
Failure to comply with these restrictions will result in a no-fit error.

## Enhanced & Fast PLLs

Stratix II devices provide robust clock management and synthesis using up to four enhanced PLLs and eight fast PLLs. These PLLs increase performance and provide advanced clock interfacing and clock-frequency synthesis. With features such as clock switchover, spread-spectrum clocking, reconfigurable bandwidth, phase control, and reconfigurable phase shifting, the Stratix II device's enhanced PLLs provide you with complete control of clocks and system timing. The fast PLLs provide general purpose clocking with multiplication and phase shifting as well as high-speed outputs for high-speed differential I/O support. Enhanced and fast PLLs work together with the Stratix II high-speed I/O and advanced clock architecture to provide significant improvements in system performance and bandwidth.

Figure 2–40 shows a top-level diagram of the Stratix II device and PLL floorplan.

**Figure 2–40. PLL Locations**



Figures 2–41 and 2–42 shows the global and regional clocking from the fast PLL outputs and the side clock pins.

**Table 2–14. DQS & DQ Bus Mode Support (Part 2 of 2)** *Note (1)*

Device	Package	Number of ×4 Groups	Number of ×8/×9 Groups	Number of ×16/×18 Groups	Number of ×32/×36 Groups
EP2S90	484-pin Hybrid FineLine BGA	8	4	0	0
	780-pin FineLine BGA	18	8	4	0
	1,020-pin FineLine BGA	36	18	8	4
	1,508-pin FineLine BGA	36	18	8	4
EP2S130	780-pin FineLine BGA	18	8	4	0
	1,020-pin FineLine BGA	36	18	8	4
	1,508-pin FineLine BGA	36	18	8	4
EP2S180	1,020-pin FineLine BGA	36	18	8	4
	1,508-pin FineLine BGA	36	18	8	4

**Notes to Table 2–14:**

- (1) Check the pin table for each DQS/DQ group in the different modes.

A compensated delay element on each DQS pin automatically aligns input DQS synchronization signals with the data window of their corresponding DQ data signals. The DQS signals drive a local DQS bus in the top and bottom I/O banks. This DQS bus is an additional resource to the I/O clocks and is used to clock DQ input registers with the DQS signal.

The Stratix II device has two phase-shifting reference circuits, one on the top and one on the bottom of the device. The circuit on the top controls the compensated delay elements for all DQS pins on the top. The circuit on the bottom controls the compensated delay elements for all DQS pins on the bottom.

Each phase-shifting reference circuit is driven by a system reference clock, which must have the same frequency as the DQS signal. Clock pins CLK[15 . . 12] p feed the phase circuitry on the top of the device and clock pins CLK[7 . . 4] p feed the phase circuitry on the bottom of the device. In addition, PLL clock outputs can also feed the phase-shifting reference circuits.

Figure 2–56 illustrates the phase-shift reference circuit control of each DQS delay shift on the top of the device. This same circuit is duplicated on the bottom of the device.



**Table 2–16. Stratix II Supported I/O Standards (Part 2 of 2)**

I/O Standard	Type	Input Reference Voltage ( $V_{REF}$ ) (V)	Output Supply Voltage ( $V_{CCIO}$ ) (V)	Board Termination Voltage ( $V_{TT}$ ) (V)
SSTL-2 Class I and II	Voltage-referenced	1.25	2.5	1.25

**Notes to Table 2–16:**

- (1) This I/O standard is only available on input and output column clock pins.
- (2) This I/O standard is only available on input clock pins and DQS pins in I/O banks 3, 4, 7, and 8, and output clock pins in I/O banks 9, 10, 11, and 12.
- (3)  $V_{CCIO}$  is 3.3 V when using this I/O standard in input and output column clock pins (in I/O banks 9, 10, 11, and 12). The clock input pins supporting LVDS on banks 3, 4, 7, and 8 use  $V_{CCINT}$  for LVDS input operations and have no dependency on the  $V_{CCIO}$  level of the bank.
- (4) 1.2-V HSTL is only supported in I/O banks 4, 7, and 8.



For more information on I/O standards supported by Stratix II I/O banks, refer to the *Selectable I/O Standards in Stratix II & Stratix II GX Devices* chapter in volume 2 of the *Stratix II Device Handbook* or the *Stratix II GX Device Handbook*.

Stratix II devices contain eight I/O banks and four enhanced PLL external clock output banks, as shown in [Figure 2–57](#). The four I/O banks on the right and left of the device contain circuitry to support high-speed differential I/O for LVDS and HyperTransport inputs and outputs. These banks support all Stratix II I/O standards except PCI or PCI-X I/O pins, and SSTL-18 Class II and HSTL outputs. The top and bottom I/O banks support all single-ended I/O standards. Additionally, enhanced PLL external clock output banks allow clock output capabilities such as differential support for SSTL and HSTL.

device, PLL 1 can drive a maximum of 10 transmitter channels in I/O bank 1 or a maximum of 19 transmitter channels in I/O banks 1 and 2. The Quartus II software may also merge receiver and transmitter PLLs when a receiver is driving a transmitter. In this case, one fast PLL can drive both the maximum numbers of receiver and transmitter channels.

**Table 2–21. EP2S15 Device Differential Channels** *Note (1)*

Package	Transmitter/ Receiver	Total Channels	Center Fast PLLs			
			PLL 1	PLL 2	PLL 3	PLL 4
484-pin FineLine BGA	Transmitter	38 (2)	10	9	9	10
		(3)	19	19	19	19
	Receiver	42 (2)	11	10	10	11
		(3)	21	21	21	21
672-pin FineLine BGA	Transmitter	38 (2)	10	9	9	10
		(3)	19	19	19	19
	Receiver	42 (2)	11	10	10	11
		(3)	21	21	21	21

**Table 2–22. EP2S30 Device Differential Channels** *Note (1)*

Package	Transmitter/ Receiver	Total Channels	Center Fast PLLs			
			PLL 1	PLL 2	PLL 3	PLL 4
484-pin FineLine BGA	Transmitter	38 (2)	10	9	9	10
		(3)	19	19	19	19
	Receiver	42 (2)	11	10	10	11
		(3)	21	21	21	21
672-pin FineLine BGA	Transmitter	58 (2)	16	13	13	16
		(3)	29	29	29	29
	Receiver	62 (2)	17	14	14	17
		(3)	31	31	31	31

you need to support configuration input voltages of 1.8 V/1.5 V, you should set the VCCSEL to a logic high and the V<sub>CCIO</sub> of the bank that contains the configuration inputs to 1.8 V/1.5 V.



For more information on multi-volt support, including information on using TDO and nCEO in multi-volt systems, refer to the *Stratix II Architecture* chapter in volume 1 of the *Stratix II Device Handbook*.

## Configuration Schemes

You can load the configuration data for a Stratix II device with one of five configuration schemes (see Table 3–5), chosen on the basis of the target application. You can use a configuration device, intelligent controller, or the JTAG port to configure a Stratix II device. A configuration device can automatically configure a Stratix II device at system power-up.

You can configure multiple Stratix II devices in any of the five configuration schemes by connecting the configuration enable (nCE) and configuration enable output (nCEO) pins on each device.

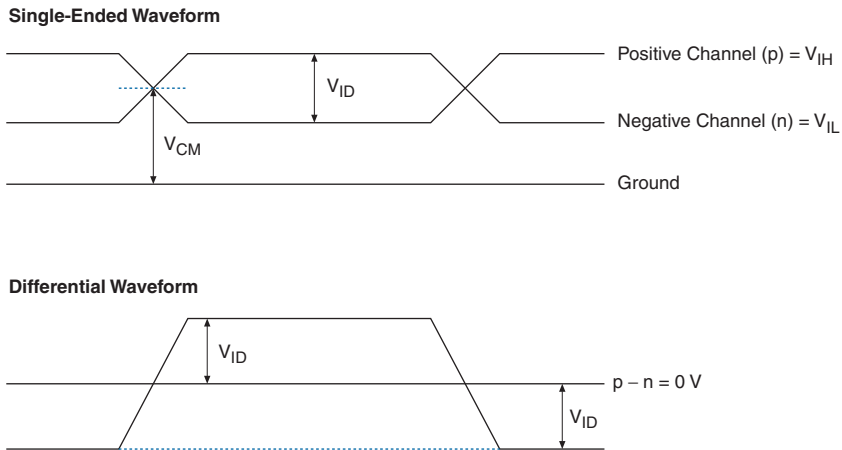
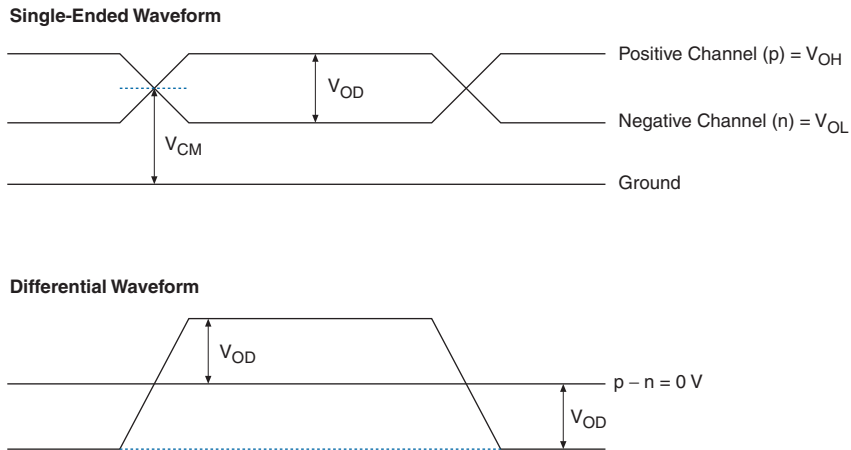
Stratix II FPGAs offer the following:

- Configuration data decompression to reduce configuration file storage
- Design security using configuration data encryption to protect your designs
- Remote system upgrades for remotely updating your Stratix II designs

Table 3–5 summarizes which configuration features can be used in each configuration scheme.

**Table 3–5. Stratix II Configuration Features (Part 1 of 2)**

Configuration Scheme	Configuration Method	Design Security	Decompression	Remote System Upgrade
FPP	MAX II device or microprocessor and flash device	✓ (1)	✓ (1)	✓
	Enhanced configuration device		✓ (2)	✓
AS	Serial configuration device	✓	✓	✓ (3)
PS	MAX II device or microprocessor and flash device	✓	✓	✓
	Enhanced configuration device	✓	✓	✓
	Download cable (4)	✓	✓	

**Figure 5–1. Receiver Input Waveforms for Differential I/O Standards****Figure 5–2. Transmitter Output Waveforms for Differential I/O Standards**

**Table 5–12. LVPECL Specifications**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{CCIO}$ (1)	I/O supply voltage		3.135	3.300	3.465	V
$V_{ID}$	Input differential voltage swing (single-ended)		300	600	1,000	mV
$V_{ICM}$	Input common mode voltage		1.0		2.5	V
$V_{OD}$	Output differential voltage (single-ended)	$R_L = 100\ \Omega$	525		970	mV
$V_{OCM}$	Output common mode voltage	$R_L = 100\ \Omega$	1,650		2,250	mV
$R_L$	Receiver differential input resistor		90	100	110	$\Omega$

**Note to Table 5–12:**

- (1) The top and bottom clock input differential buffers in I/O banks 3, 4, 7, and 8 are powered by  $V_{CCINT}$ , not  $V_{CCIO}$ . The PLL clock output/feedback differential buffers are powered by  $V_{CC\_PLL\_OUT}$ . For differential clock output/feedback operation,  $V_{CC\_PLL\_OUT}$  should be connected to 3.3 V.

**Table 5–13. HyperTransport Technology Specifications**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{CCIO}$	I/O supply voltage for left and right I/O banks (1, 2, 5, and 6)		2.375	2.500	2.625	V
$V_{ID}$	Input differential voltage swing (single-ended)	$R_L = 100\ \Omega$	300	600	900	mV
$V_{ICM}$	Input common mode voltage	$R_L = 100\ \Omega$	385	600	845	mV
$V_{OD}$	Output differential voltage (single-ended)	$R_L = 100\ \Omega$	400	600	820	mV
$\Delta V_{OD}$	Change in $V_{OD}$ between high and low	$R_L = 100\ \Omega$			75	mV
$V_{OCM}$	Output common mode voltage	$R_L = 100\ \Omega$	440	600	780	mV
$\Delta V_{OCM}$	Change in $V_{OCM}$ between high and low	$R_L = 100\ \Omega$			50	mV
$R_L$	Receiver differential input resistor		90	100	110	$\Omega$

**Table 5–14. 3.3-V PCI Specifications (Part 1 of 2)**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{CCIO}$	Output supply voltage		3.0	3.3	3.6	V
$V_{IH}$	High-level input voltage		$0.5 \times V_{CCIO}$		$V_{CCIO} + 0.5$	V

**Table 5–23. 1.5-V HSTL Class I Specifications**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{CCIO}$	Output supply voltage		1.425	1.500	1.575	V
$V_{REF}$	Input reference voltage		0.713	0.750	0.788	V
$V_{TT}$	Termination voltage		0.713	0.750	0.788	V
$V_{IH}$ (DC)	DC high-level input voltage		$V_{REF} + 0.1$			V
$V_{IL}$ (DC)	DC low-level input voltage		–0.3		$V_{REF} - 0.1$	V
$V_{IH}$ (AC)	AC high-level input voltage		$V_{REF} + 0.2$			V
$V_{IL}$ (AC)	AC low-level input voltage				$V_{REF} - 0.2$	V
$V_{OH}$	High-level output voltage	$I_{OH} = 8 \text{ mA}$ (1)	$V_{CCIO} - 0.4$			V
$V_{OL}$	Low-level output voltage	$I_{OH} = -8 \text{ mA}$ (1)			0.4	V

**Note to Table 5–23:**

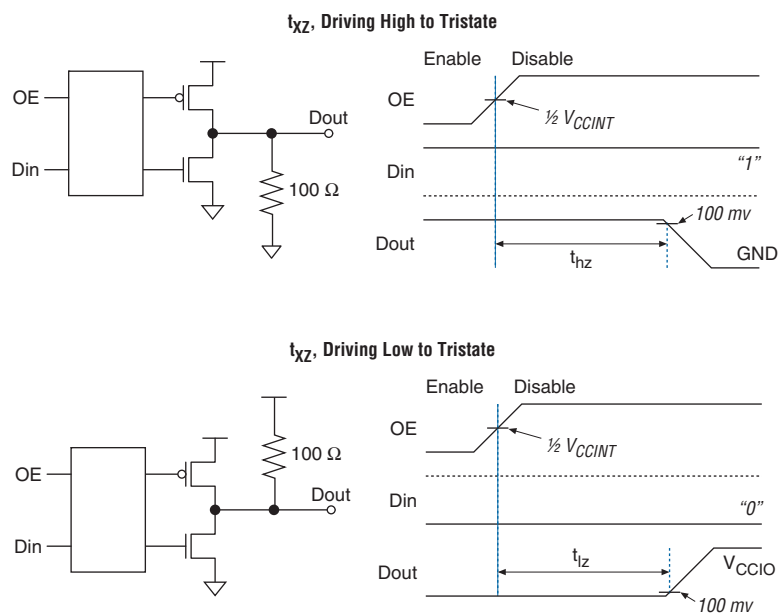
- (1) This specification is supported across all the programmable drive settings available for this I/O standard as shown in the *Stratix II Architecture* chapter in volume 1 of the *Stratix II Device Handbook*.

**Table 5–24. 1.5-V HSTL Class II Specifications**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{CCIO}$	Output supply voltage		1.425	1.500	1.575	V
$V_{REF}$	Input reference voltage		0.713	0.750	0.788	V
$V_{TT}$	Termination voltage		0.713	0.750	0.788	V
$V_{IH}$ (DC)	DC high-level input voltage		$V_{REF} + 0.1$			V
$V_{IL}$ (DC)	DC low-level input voltage		–0.3		$V_{REF} - 0.1$	V
$V_{IH}$ (AC)	AC high-level input voltage		$V_{REF} + 0.2$			V
$V_{IL}$ (AC)	AC low-level input voltage				$V_{REF} - 0.2$	V
$V_{OH}$	High-level output voltage	$I_{OH} = 16 \text{ mA}$ (1)	$V_{CCIO} - 0.4$			V
$V_{OL}$	Low-level output voltage	$I_{OH} = -16 \text{ mA}$ (1)			0.4	V

**Note to Table 5–24:**

- (1) This specification is supported across all the programmable drive settings available for this I/O standard as shown in the *Stratix II Architecture* chapter in volume 1 of the *Stratix II Device Handbook*.

**Figure 5–5. Measurement Setup for  $t_{xz}$**  *Note (1)***Note to Figure 5–5:**(1)  $V_{CCINT}$  is 1.12 V for this measurement.

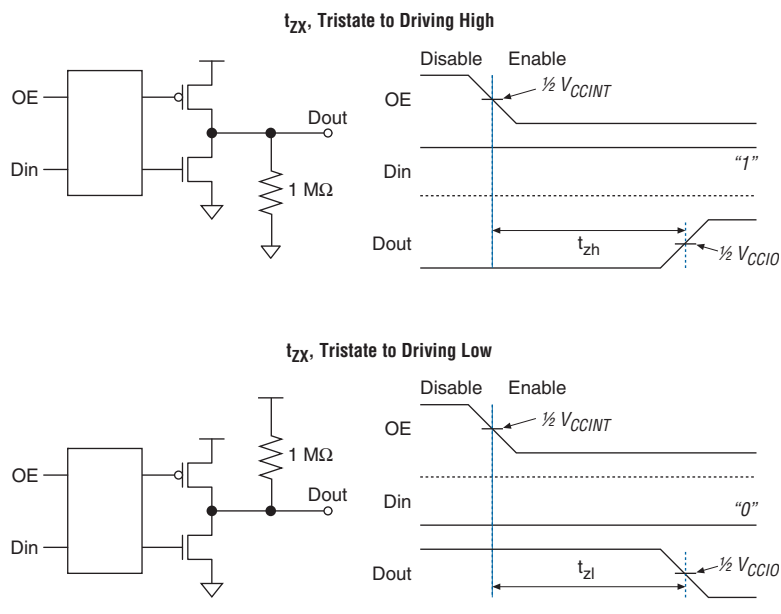
**Figure 5–6. Measurement Setup for  $t_{zx}$** 

Table 5–35 specifies the input timing measurement setup.

<b>Table 5–35. Timing Measurement Methodology for Input Pins (Part 1 of 2)</b> <i>Notes (1)–(4)</i>				
I/O Standard	Measurement Conditions			Measurement Point
	$V_{CCIO}$ (V)	$V_{REF}$ (V)	Edge Rate (ns)	$V_{MEAS}$ (V)
LVTTTL (5)	3.135		3.135	1.5675
LVC MOS (5)	3.135		3.135	1.5675
2.5 V (5)	2.375		2.375	1.1875
1.8 V (5)	1.710		1.710	0.855
1.5 V (5)	1.425		1.425	0.7125
PCI (6)	2.970		2.970	1.485
PCI-X (6)	2.970		2.970	1.485
SSTL-2 Class I	2.325	1.163	2.325	1.1625
SSTL-2 Class II	2.325	1.163	2.325	1.1625
SSTL-18 Class I	1.660	0.830	1.660	0.83
SSTL-18 Class II	1.660	0.830	1.660	0.83
1.8-V HSTL Class I	1.660	0.830	1.660	0.83



**Table 5–36. Stratix II Performance Notes (Part 6 of 6)** *Note (1)*

Applications		Resources Used			Performance				
		ALUTs	TriMatrix Memory Blocks	DSP Blocks	-3 Speed Grade (2)	-3 Speed Grade (3)	-4 Speed Grade	-5 Speed Grade	Unit
Larger designs	8-bit, 1024-point, quadrant output, four parallel FFT engines, buffered burst, three multipliers five adders FFT function	7385	60	36	359.58	352.98	312.01	278.00	MHz
	8-bit, 1024-point, quadrant output, four parallel FFT engines, buffered burst, four multipliers and two adders FFT function	6601	60	48	371.88	355.74	327.86	277.62	MHz

**Notes for Table 5–36:**

- (1) These design performance numbers were obtained using the Quartus II software version 5.0 SP1.
- (2) These numbers apply to -3 speed grade EP2S15, EP2S30, EP2S60, and EP2S90 devices.
- (3) These numbers apply to -3 speed grade EP2S130 and EP2S180 devices.
- (4) This application uses registered inputs and outputs.
- (5) This application uses registered multiplier input and output stages within the DSP block.
- (6) This application uses registered multiplier input, pipeline, and output stages within the DSP block.
- (7) This application uses registered multiplier input with output of the multiplier stage feeding the accumulator or subtractor within the DSP block.
- (8) This application uses the same clock source that is globally routed and connected to ports A and B.
- (9) This application uses locally routed clocks or differently sourced clocks for ports A and B.

**Table 5–40. M512 Block Internal Timing Microparameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	-3 Speed Grade (2)		-3 Speed Grade (3)		-4 Speed Grade		-5 Speed Grade		Unit
		Min (4)	Max	Min (4)	Max	Min (5)	Max	Min (4)	Max	
$t_{M512DATAO1}$	Clock-to-output delay when using output registers	298	478	298	501	284 298	548	298	640	ps
$t_{M512DATAO2}$	Clock-to-output delay without output registers	2,102	2,345	2,102	2,461	2,003 2,102	2,695	2,102	3,141	ps
$t_{M512CLKL}$	Minimum clock low time	1,315		1,380		1,512 1,512		1,762		ps
$t_{M512CLKH}$	Minimum clock high time	1,315		1,380		1,512 1,512		1,762		ps
$t_{M512CLR}$	Minimum clear pulse width	144		151		165 165		192		ps

**Notes to Table 5–40:**

- (1)  $F_{MAX}$  of M512 block obtained using the Quartus II software does not necessarily equal to  $1/T_{M512RC}$ .
- (2) These numbers apply to -3 speed grade EP2S15, EP2S30, EP2S60, and EP2S90 devices.
- (3) These numbers apply to -3 speed grade EP2S130 and EP2S180 devices.
- (4) For the -3 and -5 speed grades, the minimum timing is for the commercial temperature grade. Only -4 speed grade devices offer the industrial temperature grade.
- (5) For the -4 speed grade, the first number is the minimum timing parameter for industrial devices. The second number is the minimum timing parameter for commercial devices.

**Table 5–41. M4K Block Internal Timing Microparameters (Part 1 of 2)** *Note (1)*

Symbol	Parameter	-3 Speed Grade (2)		-3 Speed Grade (3)		-4 Speed Grade		-5 Speed Grade		Unit
		Min (4)	Max	Min (4)	Max	Min (5)	Max	Min (4)	Max	
$t_{M4KRRC}$	Synchronous read cycle time	1,462	2,240	1,462	2,351	1,393 1,462	2,575	1,462	3,000	ps
$t_{M4KWRESU}$	Write or read enable setup time before clock	22		23		25 25		29		ps
$t_{M4KWEREH}$	Write or read enable hold time after clock	203		213		233 233		272		ps
$t_{M4KBESU}$	Byte enable setup time before clock	22		23		25 25		29		ps
$t_{M4KBEH}$	Byte enable hold time after clock	203		213		233 233		272		ps

**Table 5–53. EP2S60 Column Pins Global Clock Timing Parameters**

Parameter	Minimum Timing		-3 Speed Grade	-4 Speed Grade	-5 Speed Grade	Unit
	Industrial	Commercial				
$t_{CIN}$	1.658	1.739	2.920	3.350	3.899	ns
$t_{COUT}$	1.501	1.574	2.678	3.072	3.575	ns
$t_{PLLCIN}$	0.06	0.057	0.278	0.304	0.355	ns
$t_{PLLCOUT}$	-0.097	-0.108	0.036	0.026	0.031	ns

**Table 5–54. EP2S60 Row Pins Regional Clock Timing Parameters**

Parameter	Minimum Timing		-3 Speed Grade	-4 Speed Grade	-5 Speed Grade	Unit
	Industrial	Commercial				
$t_{CIN}$	1.463	1.532	2.591	2.972	3.453	ns
$t_{COUT}$	1.468	1.537	2.587	2.968	3.448	ns
$t_{PLLCIN}$	-0.153	-0.167	-0.079	-0.099	-0.128	ns
$t_{PLLCOUT}$	-0.148	-0.162	-0.083	-0.103	-0.133	ns

**Table 5–55. EP2S60 Row Pins Global Clock Timing Parameters**

Parameter	Minimum Timing		-3 Speed Grade	-4 Speed Grade	-5 Speed Grade	Unit
	Industrial	Commercial				
$t_{CIN}$	1.439	1.508	2.562	2.940	3.421	ns
$t_{COUT}$	1.444	1.513	2.558	2.936	3.416	ns
$t_{PLLCIN}$	-0.161	-0.174	-0.083	-0.107	-0.126	ns
$t_{PLLCOUT}$	-0.156	-0.169	-0.087	-0.111	-0.131	ns

**Table 5–75. Stratix II I/O Output Delay for Column Pins (Part 2 of 8)**

I/O Standard	Drive Strength	Parameter	Minimum Timing		-3 Speed Grade (3)	-3 Speed Grade (4)	-4 Speed Grade	-5 Speed Grade	Unit
			Industrial	Commercial					
LVCMOS	4 mA	t <sub>OP</sub>	1041	1091	2036	2136	2340	2448	ps
		t <sub>DIP</sub>	1061	1113	2102	2206	2416	2538	ps
	8 mA	t <sub>OP</sub>	952	999	1786	1874	2053	2153	ps
		t <sub>DIP</sub>	972	1021	1852	1944	2129	2243	ps
	12 mA	t <sub>OP</sub>	926	971	1720	1805	1977	2075	ps
		t <sub>DIP</sub>	946	993	1786	1875	2053	2165	ps
	16 mA	t <sub>OP</sub>	933	978	1693	1776	1946	2043	ps
		t <sub>DIP</sub>	953	1000	1759	1846	2022	2133	ps
	20 mA	t <sub>OP</sub>	921	965	1677	1759	1927	2025	ps
		t <sub>DIP</sub>	941	987	1743	1829	2003	2115	ps
	24 mA (1)	t <sub>OP</sub>	909	954	1659	1741	1906	2003	ps
		t <sub>DIP</sub>	929	976	1725	1811	1982	2093	ps
2.5 V	4 mA	t <sub>OP</sub>	1004	1053	2063	2165	2371	2480	ps
		t <sub>DIP</sub>	1024	1075	2129	2235	2447	2570	ps
	8 mA	t <sub>OP</sub>	955	1001	1841	1932	2116	2218	ps
		t <sub>DIP</sub>	975	1023	1907	2002	2192	2308	ps
	12 mA	t <sub>OP</sub>	934	980	1742	1828	2002	2101	ps
		t <sub>DIP</sub>	954	1002	1808	1898	2078	2191	ps
	16 mA (1)	t <sub>OP</sub>	918	962	1679	1762	1929	2027	ps
		t <sub>DIP</sub>	938	984	1745	1832	2005	2117	ps

**Table 5–78. Maximum Output Toggle Rate on Stratix II Devices (Part 2 of 5)** *Note (1)*

I/O Standard	Drive Strength	Column I/O Pins (MHz)			Row I/O Pins (MHz)			Clock Outputs (MHz)		
		-3	-4	-5	-3	-4	-5	-3	-4	-5
SSTL-18 Class I	4 mA	200	150	150	200	150	150	200	150	150
	6 mA	350	250	200	350	250	200	350	250	200
	8 mA	450	300	300	450	300	300	450	300	300
	10 mA	500	400	400	500	400	400	500	400	400
	12 mA	700	550	400	-	-	-	650	550	400
SSTL-18 Class II	8 mA	200	200	150	-	-	-	200	200	150
	16 mA	400	350	350	-	-	-	400	350	350
	18 mA	450	400	400	-	-	-	450	400	400
	20 mA	550	500	450	-	-	-	550	500	450
1.8-V HSTL Class I	4 mA	300	300	300	300	300	300	300	300	300
	6 mA	500	450	450	500	450	450	500	450	450
	8 mA	650	600	600	650	600	600	650	600	600
	10 mA	700	650	600	700	650	600	700	650	600
	12 mA	700	700	650	700	700	650	700	700	650
1.8-V HSTL Class II	16 mA	500	500	450	-	-	-	500	500	450
	18 mA	550	500	500	-	-	-	550	500	500
	20 mA	650	550	550	-	-	-	550	550	550
1.5-V HSTL Class I	4 mA	350	300	300	350	300	300	350	300	300
	6 mA	500	500	450	500	500	450	500	500	450
	8 mA	700	650	600	700	650	600	700	650	600
	10 mA	700	700	650	-	-	-	700	700	650
	12 mA	700	700	700	-	-	-	700	700	700
1.5-V HSTL Class II	16 mA	600	600	550	-	-	-	600	600	550
	18 mA	650	600	600	-	-	-	650	600	600
	20 mA	700	650	600	-	-	-	700	650	600
Differential SSTL-2 Class I (3)	8 mA	400	300	300	400	300	300	400	300	300
	12 mA	400	400	350	400	400	350	400	400	350
Differential SSTL-2 Class II (3)	16 mA	350	350	300	350	350	300	350	350	300
	20 mA	400	350	350	350	350	297	400	350	350
	24 mA	400	400	350	-	-	-	400	400	350